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CLAIMS

1. A flexi-rigid printed circuit board having a rigid area, made up of inner layers of flexible copper and outer layers of rigid insulating material, and an integral flexible heat sink area having springy edge regions of exposed flexible copper layers without outer layers of rigid insulating material, and a metal heat conducting body which is springily engaged by the edge regions to provide a heat sink for the rigid areas of the board.
2. A flexi-rigid printed circuit board according to Claim 1, wherein the exposed flexible copper layers of the springy edge regions are at least partially coated with an anti corrosion material.
3. A flexi-rigid circuit board according to claim 2, wherein the anti corrosion material is at least one of tin, lead, gold.
4. A flexi-rigid printed circuit board according to anyone of Claims 1 to 3, including tubular metal thermal vias inter-connecting flexible copper layers in the rigid area to improve heat transfer between the flexible copper layers.
5. A flexi-rigid printed circuit board according to Claim 4, in which at least some of the thermal vias are located in the rigid area below parts where high heat output components are to be mounted.
6. A flexi-rigid printed circuit board according to any one of Claims 1 to 5, wherein the metal heat conducting body is a shell into which the heat sink area is a push fit and held in place by spring contact between the springy edge regions and the shell.
7. A flexi-rigid printed circuit board according to any one of Claims 1 to 6, wherein the springy edge regions are in the form of tabs extending from the rigid area.
8. A flexi-rigid printed circuit board substantially as hereinbefore described and as illustrated in any one of Figures 2 to 5 of the accompanying drawings.